TM30N02D

N-Channel Enhancement Mosfet

General Description

- Low $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

Applications

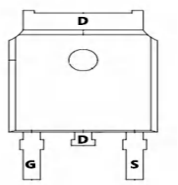
- Load switch
- PWM

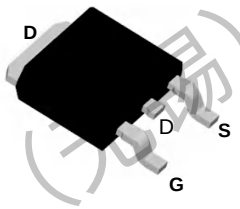
General Features

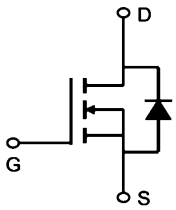
V_{DS} = 20V I_D = 30A
$R_{DS(ON)}$= 8.8mΩ(typ.) @ V_{GS}=4.5V

100% UIS Tested
100% R_g Tested

D:TO-252-3L







Marking: 30N02

Absolute Maximum Ratings (T_C = 25°C Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	±12	V
I_D@T_C=25˚C	Continuous Drain Current, V_{GS} @ 4.5V	30	A
I_D@T_C=100˚C	Continuous Drain Current, V_{GS} @ 4.5V	19	A
I_{DM}	Pulsed Drain Current	111	A
EAS	Single Pulse Avalanche Energy	12.1	mJ
I_{AS}	Avalanche Current	11	A
P_D@T_C=25˚C	Total Power Dissipation	5	W
T_{STG}	Storage Temperature Range	-55 to 150	˚C
T_J	Operating Junction Temperature Range	-55 to 150	˚C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient	---	62	˚C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case	---	6.6	˚C/W

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Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS} = 0 V, I_D = 250μA	20	-	-	V
Gate Leakage Current	I_{GSS}	V_{GS} = ±12V, V_{DS} = 0 V	-	-	±100	nA
Drain Cut-off Current	I_{DSS}	V_{DS} = 20V, V_{GS} = 0 V	-	-	1	μA
Gate Threshold Voltage	$V_{GS(th)}$	V_{GS} = V_{DS}, I_D = 250μA	0.5	0.7	0.9	V
Drain-Source On-State Resistance[3]	$R_{DS(on)}$	V_{GS} = 4.5V, I_D =5A	-	8.8	13	mΩ
		V_{GS} = 2.5V, I_D = 4.7A	-	12	20	
Dynamic Characteristics[4]						
Input Capacitance	C_{iss}	V_{GS} = 0V, V_{DS} = 10V, f = 1MHz	-	700	-	pF
Output Capacitance	C_{oss}		-	120	-	
Reverse Transfer Capacitance	C_{rss}		-	105	-	
Switching Characteristics[4]						
Total Gate Charge	Q_g	V_{GS}= 4.5V, V_{DS}= 10V, I_D= 5A	-	10.5	-	nC
Gate-Source Charge	Q_{gs}		-	2	-	
Gate-Drain Charge	Q_{gd}		-	2.5	-	
Turn-On Time	$t_{d(on)}$	V_{GEN}= 5V, V_{DD} = 10V, I_D = 5A,R_G= 3Ω,	-	10	-	ns
Rise Time	t_r		-	20	-	
Turn-Off Time	$t_{d(off)}$		-	32	-	
Fall Time	t_f		-	12	-	
Source-Drain Diode Characteristics						
Body Diode Voltage[3]	V_{SD}	I_S=4A, V_{GS} = 0V	-	-	1.2	V
Continuous Source Current	I_S		-	-	30	A

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Typical Characteristics

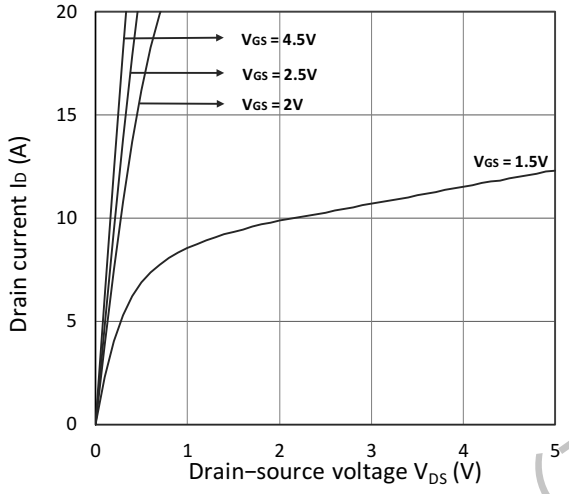

Figure 1. Output Characteristics

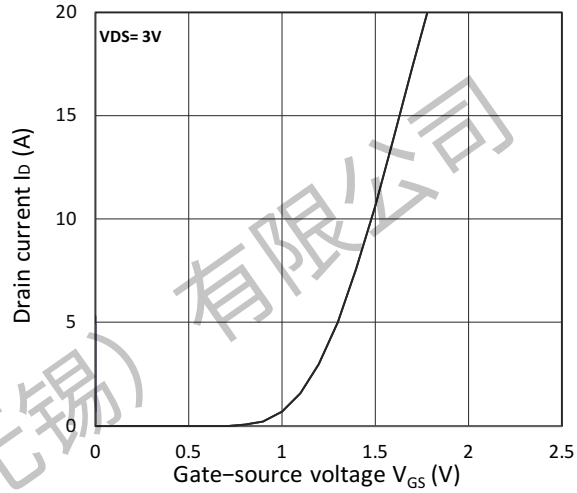

Figure 2. Transfer Characteristics

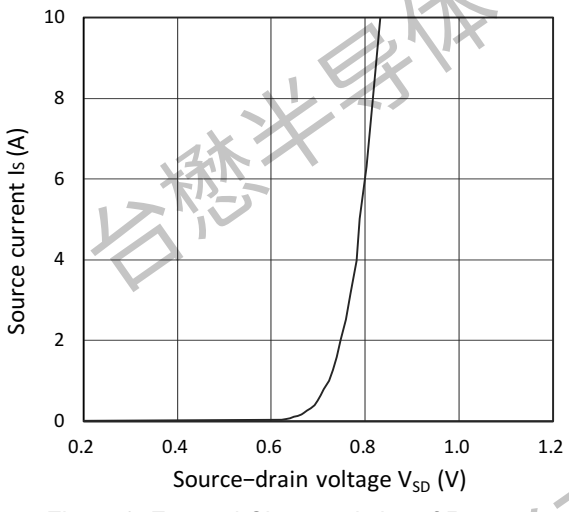

Figure 3. Forward Characteristics of Reverse

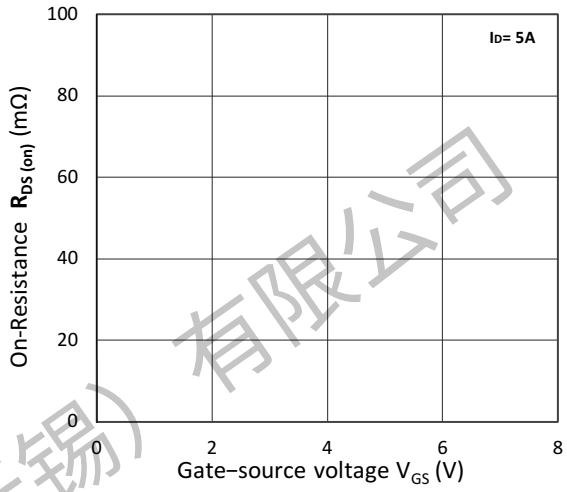

Figure 4. $R_{DS(ON)}$ vs. V_{GS}

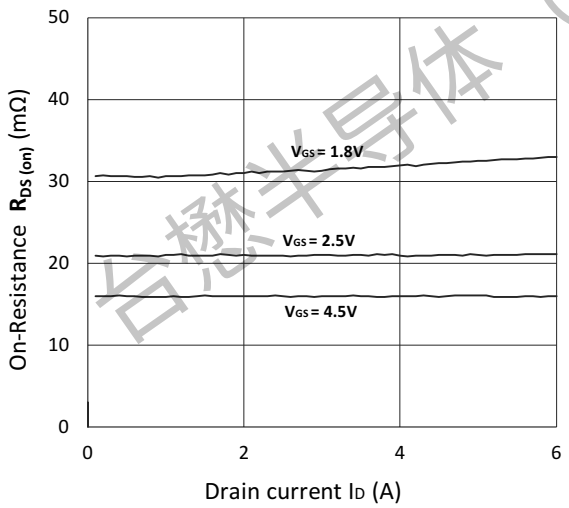

Figure 5. $R_{DS(ON)}$ vs. I_D

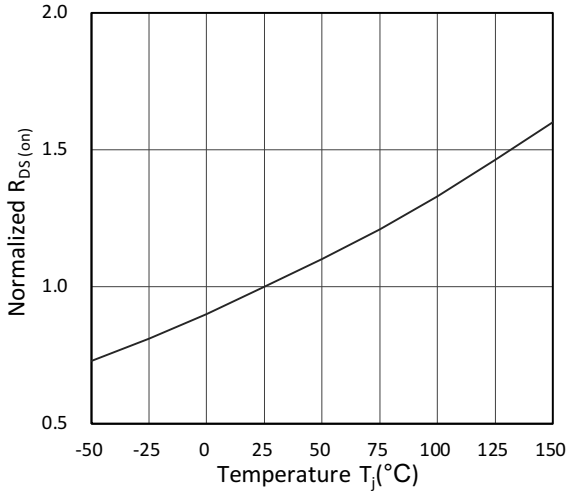

Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

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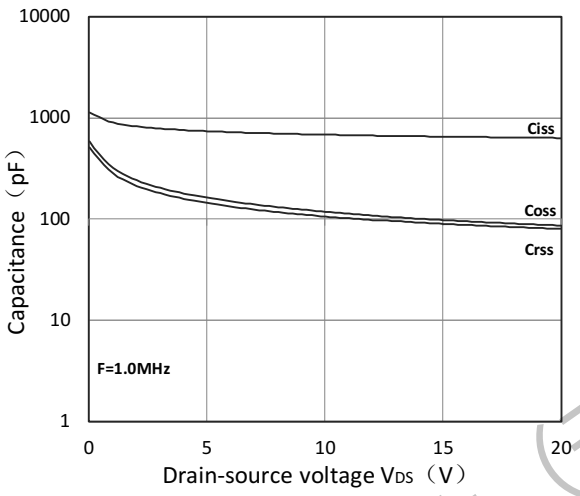

Figure 7. Capacitance Characteristics

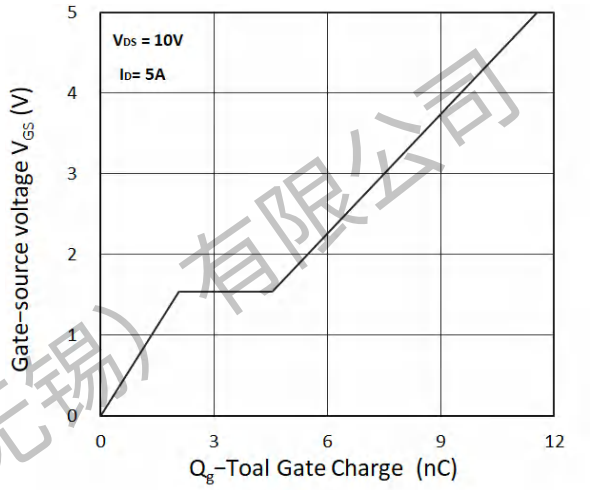

Figure 8. Gate Charge Characteristics

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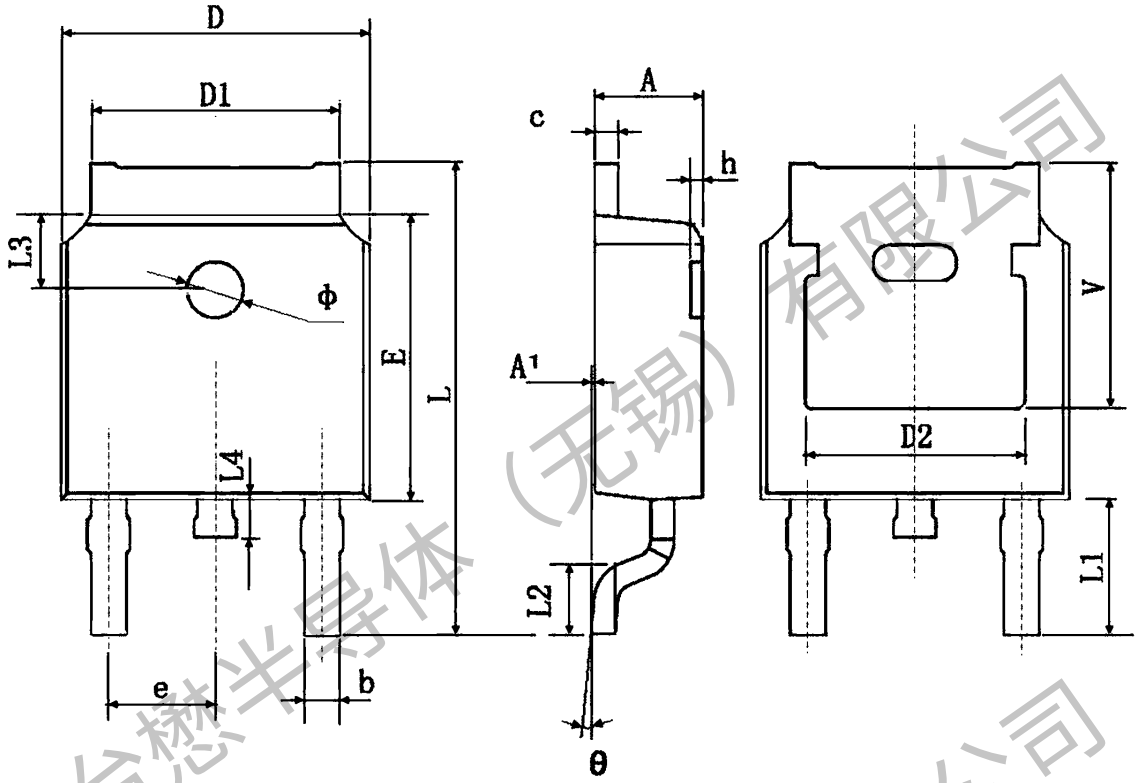

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

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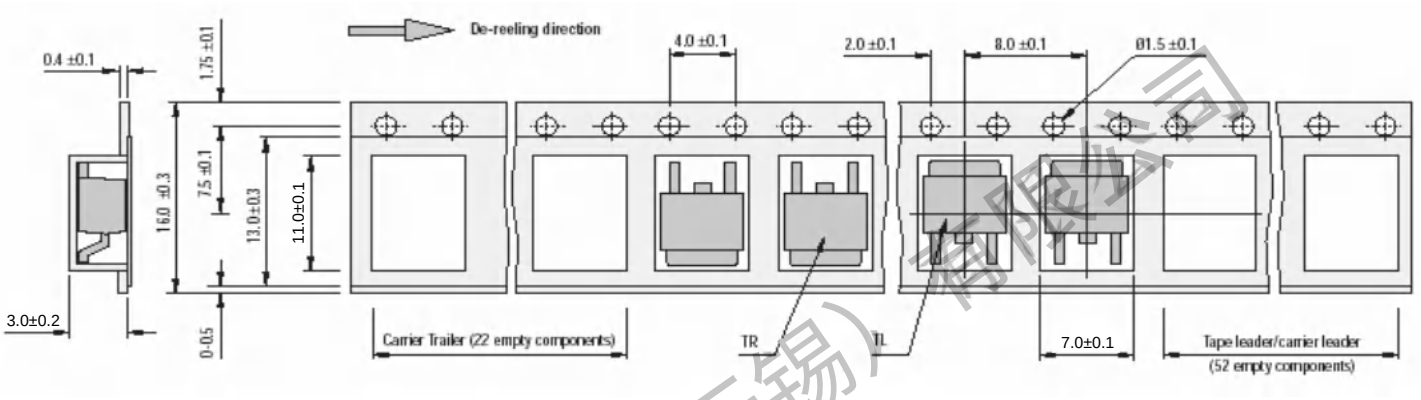
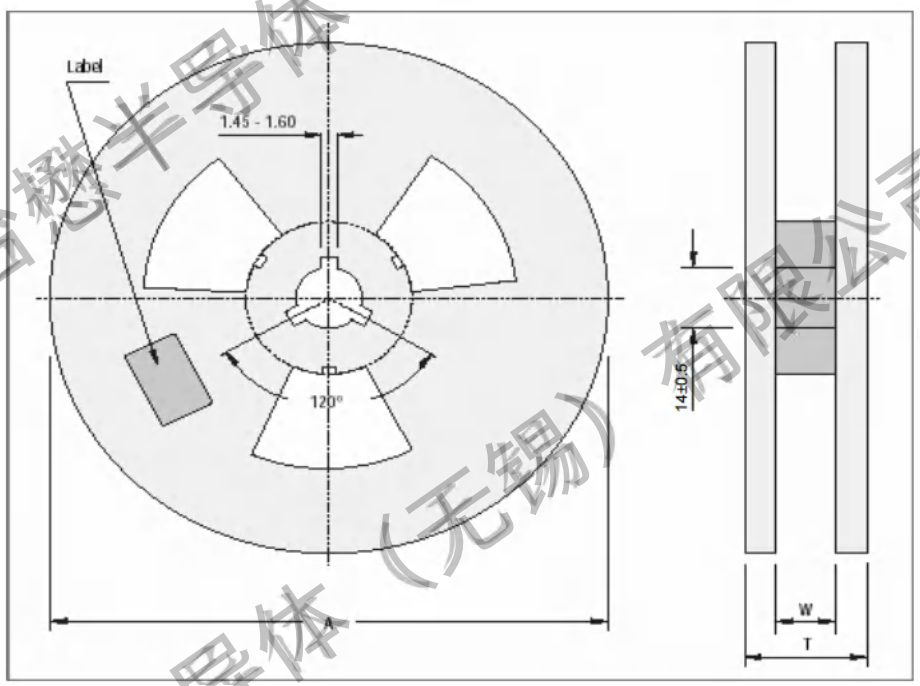
TO-252-3L Embossed Carrier Tape



TO-252-3L Reel



All Dimensions are in mm

Reel Specifications				
Package	Tape Width	Reel Dia. A - Max	Inside Thickness W	Reel Thickness T - max
TO-252-3L	16	330	18.0 ±1.5	20

Packaging Information

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
2,500 pcs	13 inch	5,000 pcs	355×370×50	25,000 pcs	380×275×380	

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Revision history:

Date	Rev	Description	Page
2023.05.09	23.05	Original	

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